

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Cheng-Hung Shih</td> <td>02/04/2012</td> </tr> <tr> <td>Yung-Wei Hsieh</td> <td>02/04/2012</td> </tr> <tr> <td>Shu-Chen Lin</td> <td>02/04/2012</td> </tr> <tr> <td>Cheng-Fan Lin</td> <td>02/04/2012</td> </tr> <tr> <td>Hua-An Dai</td> <td>02/04/2012</td> </tr> </tbody> </table>		Name	Execution Date	Cheng-Hung Shih	02/04/2012	Yung-Wei Hsieh	02/04/2012	Shu-Chen Lin	02/04/2012	Cheng-Fan Lin	02/04/2012	Hua-An Dai	02/04/2012
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Cheng-Hung Shih	02/04/2012												
Yung-Wei Hsieh	02/04/2012												
Shu-Chen Lin	02/04/2012												
Cheng-Fan Lin	02/04/2012												
Hua-An Dai	02/04/2012												
RECEIVING PARTY DATA													
Name:	CHIPBOND TECHNOLOGY CORPORATION												
Street Address:	No.3, Lihsin 5 Rd., Hsinchu Science Park												
City:	Hsinchu												
State/Country:	TAIWAN												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13426857</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13426857								
Property Type	Number												
Application Number:	13426857												
CORRESPONDENCE DATA													
Fax Number:	(866)335-6496												
Phone:	434-962-7544												
Email:	mail@jacksonipg.com												
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>													
Correspondent Name:	Demian K. Jackson												
Address Line 1:	106 Starvale Lane												
Address Line 4:	Shipman, VIRGINIA 22971												
ATTORNEY DOCKET NUMBER:	7017.146												
NAME OF SUBMITTER:	Demian K. Jackson												
Total Attachments: 3 source=ASSGN_7017_146#page1.tif source=ASSGN_7017_146#page2.tif source=ASSGN_7017_146#page3.tif													

OP \$40.00 13426857

ASSIGNMENT

WHEREAS, I (we), Cheng-Hung Shih, Yung-Wei Hsieh, Shu-Chen Lin, Cheng-Fan Lin, Hua-An Dai

whose post office address(es) appear below, hereinafter referred to as ASSIGNOR, is (are) the owner(s) of certain new and useful improvements in

METHOD FOR MANUFACTURING FINE-PITCH BUMPS AND STRUCTURE THEREOF

(Hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even date herewith

executed on:

filed on:

Serial No.:

established by PCT International Patent Application No.:

WHEREAS, CHIPBOND TECHNOLOGY CORPORATION

whose post office address is No.3, Lihsin 5 Rd., Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.

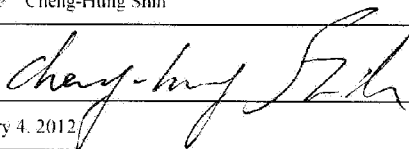
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and throughout the world;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all United States Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application; and the entire right, title and interest in and to the said INVENTION throughout the world, including the right to apply for patents and inventor certificates in respect thereof and to claim priority pursuant to rights accorded ASSIGNOR under the terms of the Paris International Convention and all other available international conventions and treaties; and the entire right, title and interest in and to any and all patents, patents of addition, utility models, patents of importation, revalidation patents and inventor certificates which may be granted throughout the world in respect of said INVENTION.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) or inventor certificate(s) in the United States and in foreign countries for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof, and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes Jackson Intellectual Property Group PLLC to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

<i>Assignor Name</i> Cheng-Hung Shih	<i>Address</i> No.48, Jinmen St., Lugang Township, Changhua County, Taiwan (R.O.C.)
<i>Where Signed</i> 	
<i>Date</i> February 4, 2012	<i>Signature</i>
_____ ss _____ (Notarization preferred but not required)	
Before me personally appeared said _____ And acknowledged this instrument to be his (her) free act and deed this _____ day of _____, _____.	
_____ <i>Notary Public</i> My Commission Expires: _____	

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<i>Assignor Name</i> Yung-Wei Hsieh	<i>Address</i> No.7, Aly. 4, Ln. 13, Chenggong Rd., North Dist., Hsinchu City, Taiwan (R.O.C.)
<i>Where Signed</i>	
<i>Date</i> February 4, 2012	<i>Signature</i> <u>Yung-Wei Hsieh</u>
_____ ss. (Notarization preferred but not required)	
Before me personally appeared said _____ And acknowledged this instrument to be his (her) free act and deed this _____ day of _____	
_____ <i>Notary Public</i> My Commission Expires: _____	

<i>Assignor Name</i> Shu-Chen Lin	<i>Address</i> No.15, Aly. 22, Ln. 383, Gongyu St., Pingtung City, Pingtung County, Taiwan (R.O.C.)
<i>Where Signed</i>	
<i>Date</i> February 4, 2012	<i>Signature</i> <u>Shu-Chen Lin</u>
_____ ss. (Notarization preferred but not required)	
Before me personally appeared said _____ And acknowledged this instrument to be his (her) free act and deed this _____ day of _____	
_____ <i>Notary Public</i> My Commission Expires: _____	

<i>Assignor Name</i> Cheng-Fan Lin	<i>Address</i> 6F., No.111, Jiafeng 1st St., Zhubei City, Hsinchu County, Taiwan (R.O.C.)
<i>Where Signed</i>	
<i>Date</i> February 4, 2012	<i>Signature</i> <u>Cheng-fan Lin</u>
_____ ss. (Notarization preferred but not required)	
Before me personally appeared said _____ And acknowledged this instrument to be his (her) free act and deed this _____ day of _____	
_____ <i>Notary Public</i> My Commission Expires: _____	

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ASSIGNMENT

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<i>Assignor Name</i> Hua-An Dai	<i>Address</i> 11F., No.22, Ln. 132, Meishu E. 2nd Rd., Gushan Dist., Kaohsiung City, Taiwan (R.O.C.)
<i>Where Signed</i>	
<i>Date</i> February 4, 2012	<i>Signature</i> <u>Hua-An Dai</u>
_____ ss. (Notarization preferred but not required)	
Before me personally appeared said _____ And acknowledged this instrument to be his (her) free act and deed this _____ day of _____	
_____ <i>Notary Public</i> My Commission Expires: _____	

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